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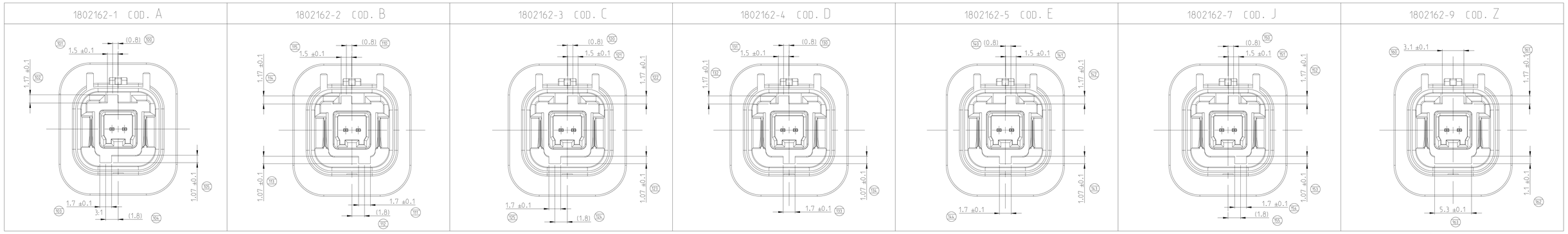
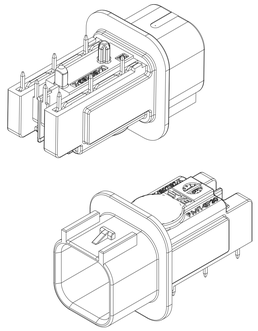
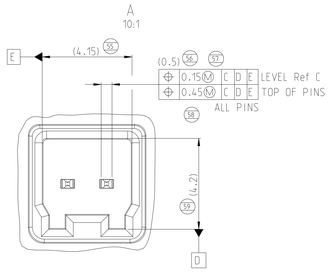
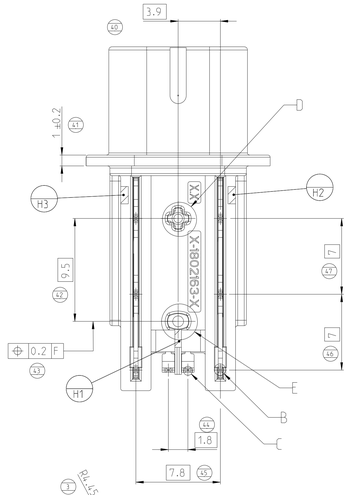
REVISIONS

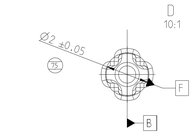
F	LTR	DESCRIPTION	DATE	DWN	APVD
	A3	UPDATE INTERFACE REVISION AND AREA FREE	22OCT2019	NS	XR
	A4	GEOM TOL UPDATED	10DEC2020	NS	XR
	A5	UPDATE NOTE AND XHATCHING	22APR2021	NS	XR
	A6	UPDATE NOTE 2	05MAY2022	NS	XR

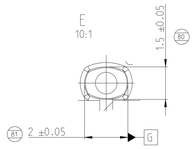


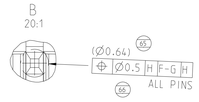


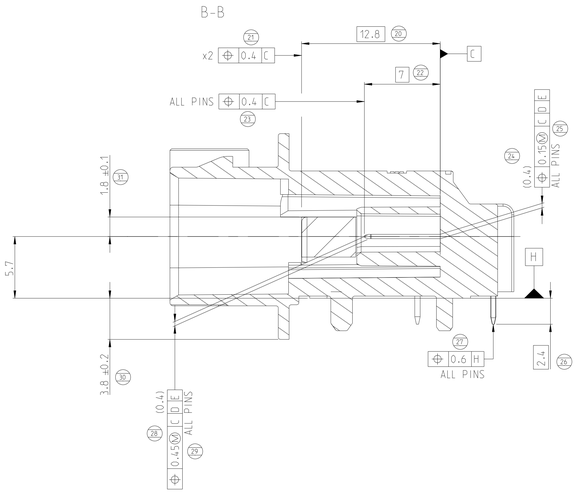


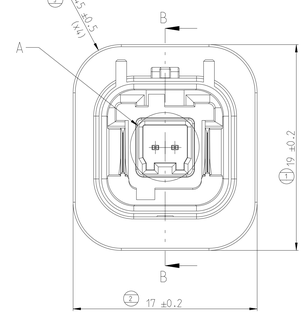


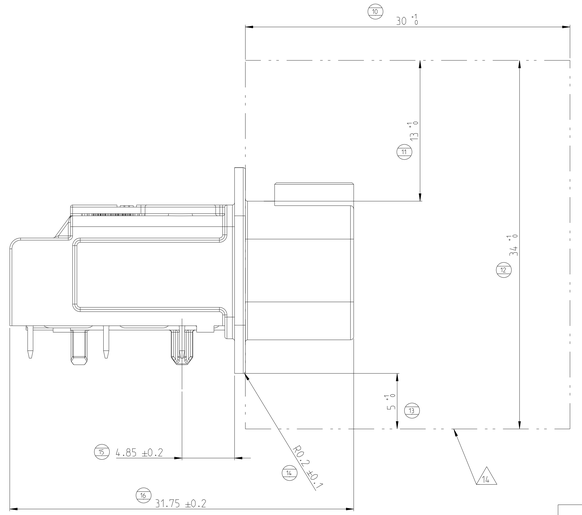


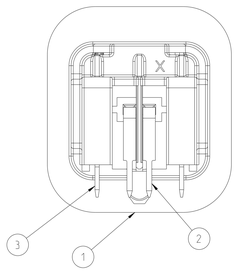


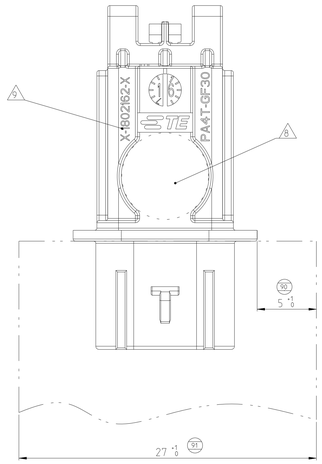






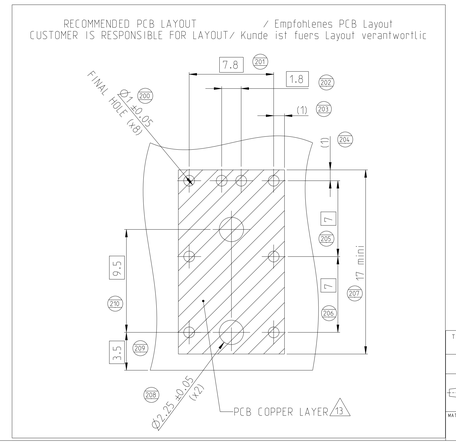






SEALED COMPONENT

FOR SERIES TOOL



GENERAL NOTES
ALLGEMEINE Bemerkungen

1 PRESS OUT FORCE FOR NANO MQS >15N WITH FEED RATE 25mm/min
Kontaktausdrueckkraft fuer NanoMQS Kontakt >15N mit Vorschubgeschwindigkeit 25mm/min

A6 2 INTERFACE AND COLOUR ACC. TO 208-18013. REV. A5.
Schnittstellen und Farbe nach 208-18013. REV. A5.

3 SOLDERING PROCESS: LEAD-FREE REFLOW SOLDERING IN REFERENCE TO JEDEC J-STD-020D
Loetprozess: Bleifreies Loeten in Anlehnung an die JEDEC J-STD-020D

4 TOLERANCE ACC. TO DIN EN ISO 8015. DIN EN ISO 14405-1
GENERAL TOL. ACC. TO DIN 16742 TG5. EXCEPT ANGLE DIM. (SEE TITLE BLOCK)
Tolerierung nach DIN EN ISO 8015. DIN EN ISO 14405-1
Allgemeintoleranzen nach DIN 16742 TG5. ausser Winkelmasse (siehe Schriftkopf)

5 PACKAGING IN TAPE & REEL ACC. TO V18021620R
Verpackung in Tape & Reel nach V18021620R

6 ELECTRICAL 100% FINAL INSPECTION FOR CONTINUITY AND SHORT CIRCUIT
AS WELL AS EXISTENCE OF ALL CONTACTS
Elektrische 100% Endpruefung auf Durchgang und Kurzschluss.
sowie das Vorhandensein aller Kontakte

7 CONTACT SURFACE
-FOR SHIELD
MATING SIDE 3-6 µm Ag OVER 1-3 µm Ni. SOLDER SIDE 3-8µm Sn OVER 1.0-2.2 µm Ni
-FOR TAB NanoMqs
MATING SIDE 3-6 µm Ag OVER 1-3 µm Ni. SOLDER SIDE 3-8µm Sn OVER 1.0-2.2 µm Ni

Kontaktoberflaeche
-Fuer Abschirmblech:
Steckseite 3-6µm Ag ueber 1-3µm Ni. Loetseitig 3-8µm Sn ueber 1.0-2.2µm Ni
- Fuer NanoMQS TAB
Steckseite 3-6µm Ag ueber 1-3µm Ni. Loetseitig 3-8µm Sn ueber 1.0-2.2µm Ni

8 VACUM GRIP AREA FREE OF BURR AND EJECTOR PINS
Ansaugflaeche frei von Grat und Auswerferstiften

9 PART NO EXCHANGEABLE ACC. TABLE
TE Einzelteilnummer austauchbar nach Tabelle

10 FOR MISSING DIMENSION SEE CAD-MODEL 2304372-X. REV. A
Fehlende Masse sind dem CAD-Model 2304372-X. Rev. A zu entnehmen

11 HEADER FULFIL RF-REQUIREMENTS UP TO 1GHz ACC. TE SPEC. 108-94509.
ALSO MANDATORY IS A PCB COPPER LAYER ACC. TO TE SPEC. 114-94448
Der Header erfuellt die RF-Anforderungnen bis zu 1 GHz nach TE Spez. 108-94509.
benfalls notwendig ist eine Leiterplatten Kupferschicht nach TE Spec. 114-94448

12 HEADER FULFIL RF-REQUIREMENTS UP TO 100 Mhz ACC. TE SPEC 108-94414
POSSIBLE FIXTURE OF HEADER WITH THE AGGREGAT CASE
Der Header erfuellt die RF-Anforderungen bis zu 100MHz nach TE Spez.108-94414
Moegliche Befestigung der Steckerleiste mit dem Aggregatdeckel

13 APPLICATION SPECIFICATION ACC. TO 114-94448
Anwendungspezifikation TE Spez. 114-94448

14 FREE SPACE FOR THE REC HSG
Freiraum fuer Buchsengehaeuse

TE ASSY NO.	CODING	REV	QTY.	DISCRIPTION	POS.
1802162-9	Z	A	2	Shield	3
		A	2	Nano MQS TAB	2
		A	1	1 Port 90° HSG COD.Z	1
1802162-7	J	A	2	Shield	3
		A	2	Nano MQS TAB	2
		A	1	1 Port 90° HSG COD.J	1
1802162-5	E	A	2	Shield	3
		A	2	Nano MQS TAB	2
		A	1	1 Port 90° HSG COD.E	1
1802162-4	D	A	2	Shield	3
		A	2	Nano MQS TAB	2
		A	1	1 Port 90° HSG COD.D	1
1802162-3	C	A	2	Shield	3
		A	2	Nano MQS TAB	2
		A	1	1 Port 90° HSG COD.C	1
1802162-2	B	A	2	Shield	3
		A	2	Nano MQS TAB	2
		A	1	1 Port 90° HSG COD. B	1
1802162-1	A	A	2	Shield	3
		A	2	Nano MQS TAB	2
		A	1	1 Port 90° HSG COD. A	1

THIS DRAWING IS A CONTROLLED DOCUMENT.
DIMENSIONS: mm
TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ±- ; 1 PLC ±- ; 2 PLC ±- ; 3 PLC ±- ; 4 PLC ±- ; ANGLES ±- ; FINISH -
MATERIAL - -

DWN N.SIMON 23OCT2017
CHK S.BERTRAND 23OCT2017
APVD X.ROUILLARD 23OCT2017
PRODUCT SPEC -
APPLICATION SPEC -
WEIGHT -

TE Connectivity

NAME HEADER 90 DEG MATEnet Sealed 1-Port

SIZE A0 | CAGE CODE 00779 | DRAWING NO C-1802162 | RESTRICTED TO

CUSTOMER DRAWING | SCALE 1:1 | SHEET 1 OF 2 | REV A6

4806 (3/13)

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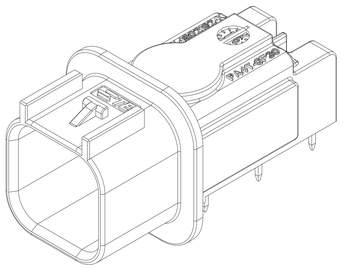
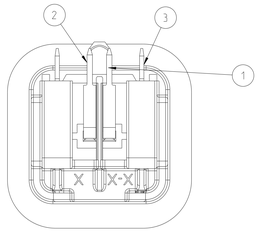
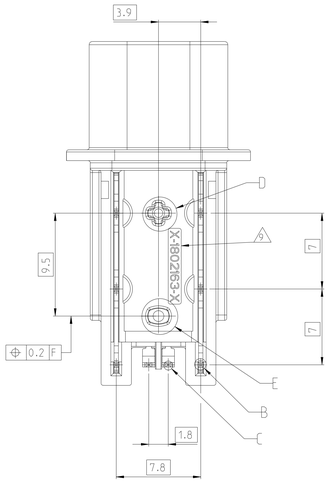
REVISIONS					
P	LTR	DESCRIPTION	DATE	DWN	APVD
	-	SEE SHEET 1	-	-	-





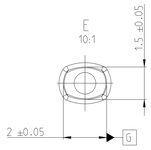


C
20:1

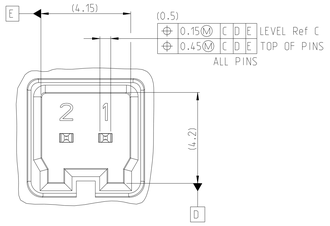
B
20:1

D
10:1

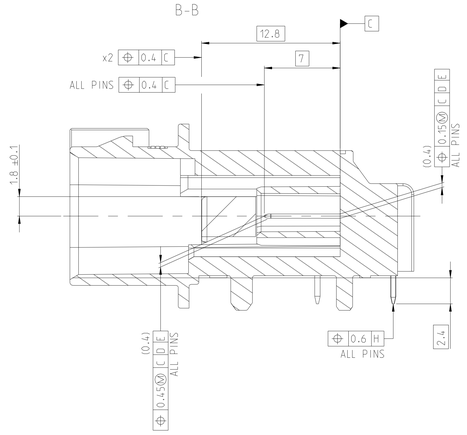
E
10:1

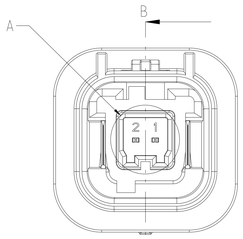


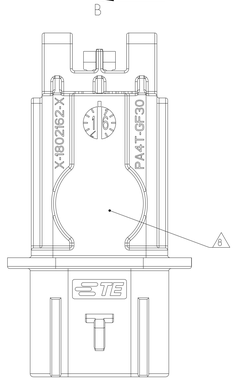
A
10:1



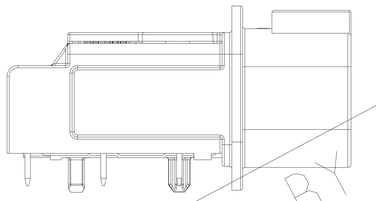
B-B







A6



GENERAL NOTES
ALLGEMEINE Bemerkungen

1 PRESS OUT FORCE FOR NANO MQS >15N WITH FEED RATE 25mm/min
Kontaktausdrueckkraft der Nano MQS Kontakte >15N mit Vorschubgeschwindigkeit 25mm/min.

2 INTERFACE ACC. TO 208-18013. REV. A1. 06 APR 2016
Schnittstelle nach 208-18013. Rev.A1 vom 06.04.2016

3 -
-

4 TOLERANCE ACC. TO DIN EN ISO 8015. DIN EN ISO 14405-1
GENERAL TOL. ACC. TO DIN 16742 TG5. EXCEPT ANGLE DIM. (SEE TITLE BLOCK)
Tolerierung nach DIN EN ISO 8015. DIN EN ISO 14405-1
Allgemeintoleranzen nach DIN 16742 TG5. ausser Winkelmasse (siehe Schriftkopf)

5 PACKAGING ACC. TO V18021620R EQUIVALENT TAPE & REEL
Verpackung nach V1802162 Tape & Reel

6 -
-

7 CONTACT SURFACE
-FOR SHIELD
MATING SIDE 1-3 µm Sn OVER 1.0-2.2 µm Ni. SOLDER SIDE 3-8µm Sn OVER 1.0-2.2 µm Ni
Kontaktoberflaeche
Steckseitig 1-3 µm Sn ueber 1.0-2.2 µm Ni. Loetseitig 3-8µm Sn ueber 1.0-2.2 µm Ni

-FOT TAB NanoMqs
MATING SIDE 3-6 µm Ag OVER 1-3 µm Ni. SOLDER SIDE 3-8µm Sn OVER 1.0-2.2 µm Ni
Kontaktoberflaeche
Steckseitig 3-6 µm Ag ueber 1-3 µm Ni. Loetseitig 3-8µm Sn ueber 1.0-2.2 µm Ni

8 VACUM GRIP AREA
Ansaugflaeche

9 PART NO EXCHANGEABLE ACC. TABLE
Teile Nr. auswechselbar nach Tabelle

10 SOLDERING PROCESS: LEAD-FREE REFLOW SOLDERING IN REFERENCE TO JEDEC J-STD-020D
Loetprozess: Bleifreies Reflowloeten in Anlehnung an die JEDEC J-STD-020D

11 HEADER FULFIL RF-REQUIREMENTS UP TO 1GHz ACC. TE SPEC. 108-94509. ALSO MANDATORY IS A PCB COPPER LAYER ACC. TO TE SPEC. 114-94448
Der Header erfuellt die RF-Anforderungen bis zu 1 GHz nach TE Spez. 108-94509. Ebenfalls notwendig ist eine Leiterplatten Kupferschicht nach TE Spec. 108-94509

12 HEADER FULFIL RF-REQUIREMENTS UP TO 100 Mhz ACC. TE SPEC 108-94414
Der Header erfuellt die RF-Anforderungen bis zu 100MHz nach TE Spez.108-94414

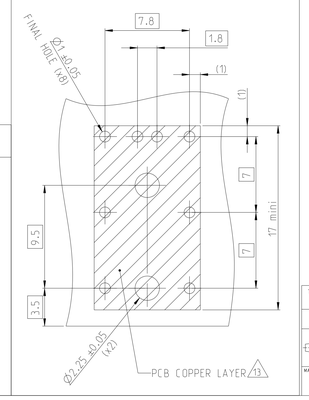
POSSIBLE FIXTURE OF HEADER WITH THE AGGREGAT CASE
Mogliche Fixierung des Header durch das Aggregat Gehaeuse

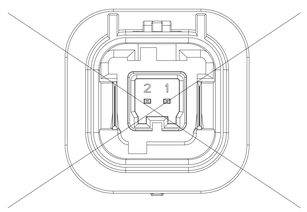
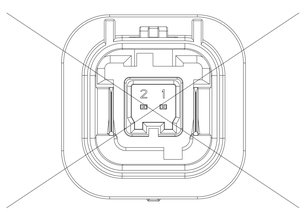
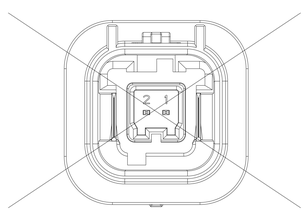
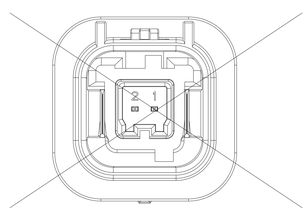
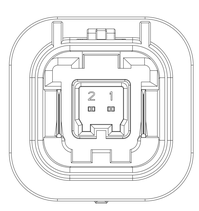
13 APPLICATION SPECIFICATION ACC. TO 114-94448
Anwendungspezifikation TE Spez. 114-94448

OBSOLETE: REPLACED BY SERIAL COMPONENT
SEE SHEET 1

FOR PROTOTYPE B-SAMPLE ONLY
NUR FUER B-MUSTER

RECOMMENDED PCB LAYOUT



9-1802162-1 COD. A	9-1802162-2 COD. B	9-1802162-3 COD. C	9-1802162-7 COD. J	9-1802162-9 COD. Z
				

TE ASSY NO.	CODING	REV	QTY.	DISCRIPTION	POS.
9-1802162-9	Z	A	2	Shield	3
		A	2	Nano MQS TAB	2
		A	1	1 Port 90° HSG COD.Z	1
~~9-1802162-7~~	J	A	2	Shield	3
		A	2	Nano MQS TAB	2
		A	1	1 Port 90° HSG COD.J	1
~~9-1802162-3~~	C	A	2	Shield	3
		A	2	Nano MQS TAB	2
		A	1	1 Port 90° HSG COD.C	1
~~9-1802162-2~~	B	A	2	Shield	3
		A	2	Nano MQS TAB	2
		A	1	1 Port 90° HSG COD. B	1
~~9-1802162-1~~	A	A	2	Shield	3
		A	2	Nano MQS TAB	2
		A	1	1 Port 90° HSG COD. A	1

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm

TOLERANCES UNLESS OTHERWISE SPECIFIED:
0 PLC ±-
1 PLC ±-
2 PLC ±-
3 PLC ±-
4 PLC ±-
ANGLES ±-

MATERIAL - -
FINISH - -

DRN	M.SIMON	23OCT2017
CHK	S.BERTRAND	23OCT2017
APVD	X.GOUILLARD	23OCT2017
PRODUCT SPEC	-	
APPLICATION SPEC	-	
WEIGHT	-	

CUSTOMER DRAWING

TE Connectivity

NAME: HEADER 90 DEG MATEnet Sealed 1-Port

SIZE	CAGE CODE	DRAWING NO	RESTRICTED TO
A0	00779	C-1802162	

SCALE 5:1 SHEET 2 OF 2 REV A6